

Docket No.: JCLA8533

Application No.: 10/055,568

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**NOV 08 2004****IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In Re Application of:

LIN ET AL.

Serial No.: 10/055,568

Filed: January 22, 2002

For: INTEGRATED CHIP PACKAGE  
STRUCTURE USING SILICON  
SUBSTRATE AND METHOD OF  
MANUFACTURING THE SAME

Examiner: MITCHELL, JAMES M

Art Unit: 2827

Docket No.: JCLA8533

**PRELIMINARY AMENDMENT**COMMISSIONER FOR PATENTS  
P.O. Box 1450  
Mail Stop RCE  
Alexandria, Virginia 22313-1450

Dear Sir:

This Preliminary Amendment is filed together with a Request for Continued Examination (RCE). The Office Action mailed June 8, 2004 has been carefully considered. In response thereto, please enter the following amendments and consider the following remarks.